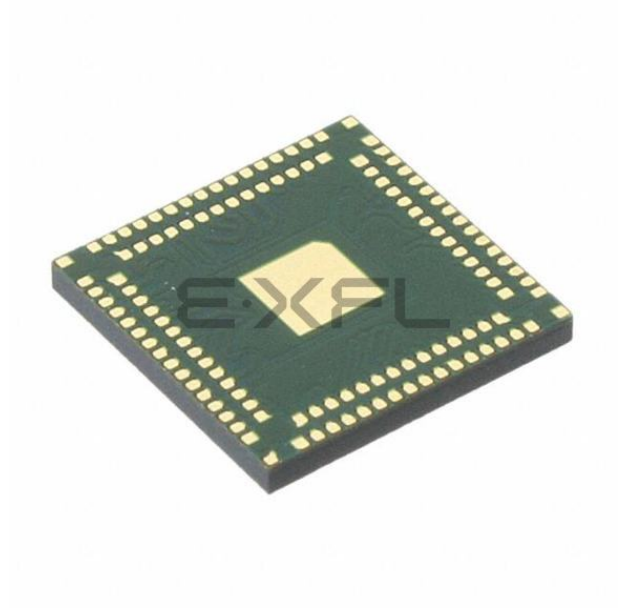


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	XCore
Core Size	32-Bit 10-Core
Speed	1000MIPS
Connectivity	Configurable
Peripherals	-
Number of I/O	84
Program Memory Size	128KB (32K x 32)
Program Memory Type	SRAM
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	0.95V ~ 3.6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	124-TFQFN Dual Rows, Exposed Pad
Supplier Device Package	124-QFN DualRow (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/xmos/xs1-l10a-128-qf124-c10

2 XS1-L10A-128-QF124 Features

- **Multicore Microcontroller with Advanced Multi-Core RISC Architecture**
  - 10 real-time logical cores on 2 xCORE tiles
  - Cores share up to 500 MIPS
  - Each logical core has:
    - Guaranteed throughput of between 1/4 and 1/5 of tile MIPS
    - 16x32bit dedicated registers
  - 159 high-density 16/32-bit instructions
    - All have single clock-cycle execution (except for divide)
    - 32x32→64-bit MAC instructions for DSP, arithmetic and user-definable cryptographic functions
- **Programmable I/O**
  - 28 general-purpose I/O pins, configurable as input or output
    - Up to 32 x 1bit port, 12 x 4bit port, 7 x 8bit port, 3 x 16bit port
    - 4 xCONNECT links
  - Port sampling rates of up to 60 MHz with respect to an external clock
  - 64 channel ends for communication with other cores, on or off-chip
- **Memory**
  - 128KB internal single-cycle SRAM (max 64KB per tile) for code and data storage
  - 8KB internal OTP (max 8KB per tile) for application boot code
- **Hardware resources**
  - 12 clock blocks (6 per tile)
  - 20 timers (10 per tile)
  - 8 locks (4 per tile)
- **JTAG Module for On-Chip Debug**
- **Security Features**
  - Programming lock disables debug and prevents read-back of memory contents
  - AES bootloader ensures secrecy of IP held on external flash memory
- **Ambient Temperature Range**
  - Commercial qualification: 0°C to 70°C
  - Industrial qualification: -40°C to 85°C
- **Speed Grade**
  - 10: 1000 MIPS
  - 8: 800 MIPS
- **Power Consumption**
  - Active Mode
    - 400 mA at 500 MHz (typical)
    - 320 mA at 400 MHz (typical)
  - Standby Mode
    - 28 mA
- **124-pin QF124 package 0.5 mm pitch**

Signal	Function					Type	Properties
X1D00	$1A^0$					I/O	PD_S, R_S
X1D01	XLA^4_{out}	$1B^0$				I/O	PD_S, R_S
X1D02	XLA^3_{out}	$4A^0$	$8A^0$	$16A^0$	$32A^{20}$	I/O	PD_S, R_U
X1D03	XLA^2_{out}	$4A^1$	$8A^1$	$16A^1$	$32A^{21}$	I/O	PD_S, R_U
X1D04	XLA^1_{out}	$4B^0$	$8A^2$	$16A^2$	$32A^{22}$	I/O	PD_S, R_U
X1D05	XLA^0_{out}	$4B^1$	$8A^3$	$16A^3$	$32A^{23}$	I/O	PD_S, R_U
X1D06	XLA^0_{in}	$4B^2$	$8A^4$	$16A^4$	$32A^{24}$	I/O	PD_S, R_U
X1D07	XLA^1_{in}	$4B^3$	$8A^5$	$16A^5$	$32A^{25}$	I/O	PD_S, R_U
X1D08	XLA^2_{in}	$4A^2$	$8A^6$	$16A^6$	$32A^{26}$	I/O	PD_S, R_U
X1D09	XLA^3_{in}	$4A^3$	$8A^7$	$16A^7$	$32A^{27}$	I/O	PD_S, R_U
X1D10	XLA^4_{in}	$1C^0$				I/O	PD_S, R_S
X1D11	$1D^0$					I/O	PD_S, R_S
X1D12	$1E^0$					I/O	PD_S, R_U
X1D13	XLB^4_{out}	$1F^0$				I/O	PD_S, R_U
X1D14	XLB^3_{out}	$4C^0$	$8B^0$	$16A^8$	$32A^{28}$	I/O	PD_S, R_U
X1D15	XLB^2_{out}	$4C^1$	$8B^1$	$16A^9$	$32A^{29}$	I/O	PD_S, R_U
X1D16	XLB^1_{out}	$4D^0$	$8B^2$	$16A^{10}$		I/O	PD_S, R_U
X1D17	XLB^0_{out}	$4D^1$	$8B^3$	$16A^{11}$		I/O	PD_S, R_U
X1D18	XLB^0_{in}	$4D^2$	$8B^4$	$16A^{12}$		I/O	PD_S, R_U
X1D19	XLB^1_{in}	$4D^3$	$8B^5$	$16A^{13}$		I/O	PD_S, R_U
X1D20	XLB^2_{in}	$4C^2$	$8B^6$	$16A^{14}$	$32A^{30}$	I/O	PD_S, R_U
X1D21	XLB^3_{in}	$4C^3$	$8B^7$	$16A^{15}$	$32A^{31}$	I/O	PD_S, R_U
X1D22	XLB^4_{in}	$1G^0$				I/O	PD_S, R_U
X1D23	$1H^0$					I/O	PD_S, R_U
X1D24	$1I^0$					I/O	PD_S
X1D25	$1J^0$					I/O	PD_S
X1D26		$4E^0$	$8C^0$	$16B^0$		I/O	PD_S, R_U
X1D27		$4E^1$	$8C^1$	$16B^1$		I/O	PD_S, R_U
X1D28		$4F^0$	$8C^2$	$16B^2$		I/O	PD_S, R_U
X1D29		$4F^1$	$8C^3$	$16B^3$		I/O	PD_S, R_U
X1D30		$4F^2$	$8C^4$	$16B^4$		I/O	PD_S, R_U
X1D31		$4F^3$	$8C^5$	$16B^5$		I/O	PD_S, R_U
X1D32		$4E^2$	$8C^6$	$16B^6$		I/O	PD_S, R_U
X1D33		$4E^3$	$8C^7$	$16B^7$		I/O	PD_S, R_U
X1D34	$1K^0$					I/O	PD_S
X1D35	$1L^0$					I/O	PD_S
X1D36	$1M^0$		$8D^0$	$16B^8$		I/O	PD_S
X1D37	$1N^0$		$8D^1$	$16B^9$		I/O	PD_S, R_U
X1D38	$1O^0$		$8D^2$	$16B^{10}$		I/O	PD_S, R_U
X1D39	$1P^0$		$8D^3$	$16B^{11}$		I/O	PD_S, R_U

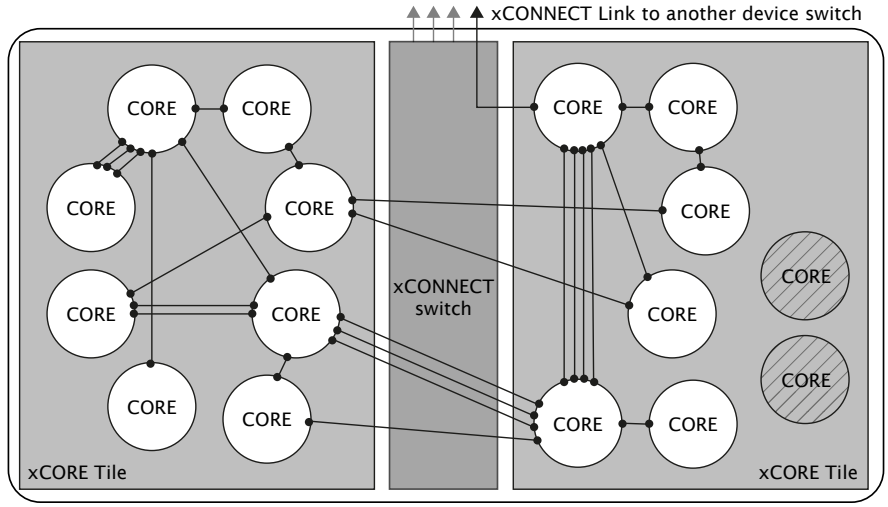


Figure 5: Switch, links and channel ends

Information on the supported routing topologies that can be used to connect multiple devices together can be found in the XS1-L Link Performance and Design Guide, X2999.

6 PLL

The PLL creates a high-speed clock that is used for the switch, tile, and reference clock.

The PLL multiplication value is selected through the two MODE pins, and can be changed by software to speed up the tile or use less power. The MODE pins are set as shown in Figure 6:

Figure 6: PLL multiplier values and MODE pins

Oscillator Frequency	MODE 1	MODE 0	Tile Frequency	PLL Ratio	PLL settings OD	F	R
5-13 MHz	0	0	130-399.75 MHz	30.75	1	122	0
13-20 MHz	1	1	260-400.00 MHz	20	2	119	0
20-48 MHz	1	0	167-400.00 MHz	8.33	2	49	0
48-100 MHz	0	1	196-400.00 MHz	4	2	23	0

Figure 6 also lists the values of OD, F and R, which are the registers that define the ratio of the tile frequency to the oscillator frequency:

$$F_{core} = F_{osc} \times \frac{F+1}{2} \times \frac{1}{R+1} \times \frac{1}{OD+1}$$

MODE [4]	MODE [3]	MODE [2]	Boot Source
X	0	0	None: Device waits to be booted via JTAG
X	0	1	Reserved
0	1	0	Tile0 boots from link B, Tile1 from channel end 0 via Tile0
0	1	1	Tile0 boots from SPI, Tile1 from channel end 0 via Tile0
1	1	0	Tile0 and Tile1 independently enable link B and internal links (E, F, G, H), and boot from channel end 0
1	1	1	Tile0 and Tile 1 boot from SPI independently

Figure 8: Boot source pins

The program size and CRC are stored least significant byte first. The program is loaded into the lowest memory address of RAM, and the program is started from that address. The CRC is calculated over the byte stream represented by the program size and the program itself. The polynomial used is 0xEDB88320 (IEEE 802.3); the CRC register is initialized with 0xFFFFFFFF and the residue is inverted to produce the CRC.

7.1 Boot from SPI master

If set to boot from SPI master, the processor enables the four pins specified in Figure 9, and drives the SPI clock at 2.5 MHz (assuming a 400 MHz core clock). A READ command is issued with a 24-bit address 0x000000. The clock polarity and phase are 0 / 0.

Pin	Signal	Description
X0D00	MISO	Master In Slave Out (Data)
X0D01	SS	Slave Select
X0D10	SCLK	Clock
X0D11	MOSI	Master Out Slave In (Data)

Figure 9: SPI master pins

The xCORE Tile expects each byte to be transferred with the *least-significant bit first*. Programmers who write bytes into an SPI interface using the most significant bit first may have to reverse the bits in each byte of the image stored in the SPI device.

If a large boot image is to be read in, it is faster to first load a small boot-loader that reads the large image using a faster SPI clock, for example 50 MHz or as fast as the flash device supports.

The pins used for SPI boot are hardcoded in the boot ROM and cannot be changed. If required, an SPI boot program can be burned into OTP that uses different pins.

7.2 Boot from xConnect Link

If set to boot from an xConnect Link, the processor enables Link B around 200 ns after the boot process starts. Enabling the Link switches off the pull-down on

resistors X0D16..X0D19, drives X0D16 and X0D17 low (the initial state for the Link), and monitors pins X0D18 and X0D19 for boot-traffic. X0D18 and X0D19 must be low at this stage. If the internal pull-down is too weak to drain any residual charge, external pull-downs of 10K may be required on those pins.

The boot-rom on the core will then:

1. Allocate channel-end 0.
2. Input a word on channel-end 0. It will use this word as a channel to acknowledge the boot. Provide the null-channel-end 0x0000FF02 if no acknowledgment is required.
3. Input the boot image specified above, including the CRC.
4. Input an END control token.
5. Output an END control token to the channel-end received in step 2.
6. Free channel-end 0.
7. Jump to the loaded code.

7.3 Boot from OTP

If an xCORE tile is set to use secure boot (see Figure 7), the boot image is read from address 0 of the OTP memory in the tile's security module.

This feature can be used to implement a secure bootloader which loads an encrypted image from external flash, decrypts and CRC checks it with the processor, and discontinues the boot process if the decryption or CRC check fails. XMOS provides a default secure bootloader that can be written to the OTP along with secret decryption keys.

Each tile has its own individual OTP memory, and hence some tiles can be booted from OTP while others are booted from SPI or the channel interface. This enables systems to be partially programmed, dedicating one or more tiles to perform a particular function, leaving the other tiles user-programmable.

7.4 Security register

The security register enables security features on the xCORE tile. The features shown in Figure 10 provide a strong level of protection and are sufficient for providing strong IP security.

8 Memory

8.1 OTP

Each xCORE Tile integrates 8 KB one-time programmable (OTP) memory along with a security register that configures system wide security features. The OTP holds

- PLL_AGND for PLL_AVDD
- GND for all other supplies

All ground pins must be connected directly to the board ground.

The VDD and VDDIO supplies should be decoupled close to the chip by several 100 nF low inductance multi-layer ceramic capacitors between the supplies and GND (for example, 4x100nF 0402 low inductance MLCCs per supply rail). The ground side of the decoupling capacitors should have as short a path back to the GND pins as possible. A bulk decoupling capacitor of at least 10 uF should be placed on each of these supplies.

RST_N is an active-low asynchronous-assertion global reset signal. Following a reset, the PLL re-establishes lock after which the device boots up according to the boot mode (*see* §7). RST_N and must be asserted low during and after power up for 100 ns.

10.1 Land patterns and solder stencils

The land pattern recommendations in this document are based on a RoHS compliant process and derived, where possible, from the nominal *Generic Requirements for Surface Mount Design and Land Pattern Standards* IPC-7351B specifications. This standard aims to achieve desired targets of heel, toe and side fillets for solder-joints.

Solder paste and ground via recommendations are based on our engineering and development kit board production. They have been found to work and optimized as appropriate to achieve a high yield. The size, type and number of vias used in the center pad affects how much solder wicks down the vias during reflow. This in turn, along with solder paster coverage, affects the final assembled package height. These factors should be taken into account during design and manufacturing of the PCB.

The following land patterns and solder paste contains recommendations. Final land pattern and solder paste decisions are the responsibility of the customer. These should be tuned during manufacture to suit the manufacturing process.

The package is a 124 pin dual row Quad Flat No lead package with exposed heat slug on a 0.5mm pitch. An example land pattern is shown in Figure 14.

Pad widths and spacings are such that solder mask can still be applied between the pads using standard design rules. This is highly recommended to reduce solder shorts between pads. See the recommended PCB solder mask diagram in Figure 15.

10.2 Solder Stencil

The solder joints in the QFN package are formed exclusively from the solder paste deposited from the solder stencil. At the small aperture sizes required, the design of the stencil becomes important to ensure a reliable final solder joint volume and reliable solder joints.

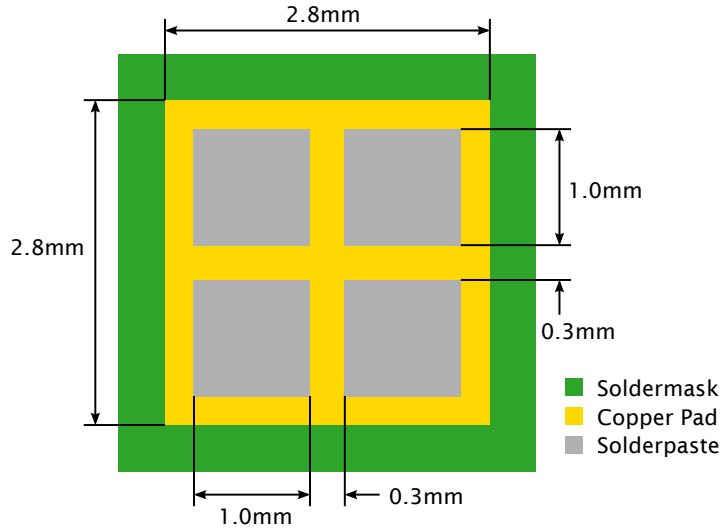


Figure 17: Solder stencil for centre pad

All XMOS devices are Moisture Sensitivity Level (MSL) 3 - devices have a shelf life of 168 hours between removal from the packaging and reflow, provided they are stored below 30C and 60% RH. If devices have exceeded these values or an included moisture indicator card shows excessive levels of moisture, then the parts should be baked as appropriate before use. This is based on information from *Joint IPC/JEDEC Standard For Moisture/Reflow Sensitivity Classification For Nonhermetic Solid State Surface-Mount Devices* J-STD-020 Revision D.

11 DC and Switching Characteristics

11.1 Operating Conditions

Figure 18: Operating conditions

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
VDD	Tile DC supply voltage	0.95	1.00	1.05	V	
VDDIO	I/O supply voltage	3.00	3.30	3.60	V	
PLL_AVDD	PLL analog supply	0.95	1.00	1.05	V	
PCU_VDD	PCU tile DC supply voltage	0.95	1.00	1.05	V	
PCU_VDDIO	PCU I/O DC supply voltage	3.00	3.30	3.60	V	
OTP_VCC	OTP supply voltage	3.00	3.30	3.60	V	
Cl	xCORE Tile I/O load capacitance			25	pF	
Ta	Ambient operating temperature (Commercial)	0		70	˚C	
	Ambient operating temperature (Industrial)	-40		85	˚C	
Tj	Junction temperature			125	˚C	
Tstg	Storage temperature	-65		150	˚C	

11.2 DC Characteristics

Figure 19: DC characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
V(IH)	Input high voltage	2.00		3.60	V	A
V(IL)	Input low voltage	-0.30		0.70	V	A
V(OH)	Output high voltage	2.00			V	B, C
V(OL)	Output low voltage			0.60	V	B, C
R(PU)	Pull-up resistance		35K		Ω	D
R(PD)	Pull-down resistance		35K		Ω	D

A All pins except power supply pins.

B Ports 1A, 1D, 1E, 1H, 1I, 1J, 1K and 1L are nominal 8 mA drivers, the remainder of the general-purpose I/Os are 4 mA.

C Measured with 4 mA drivers sourcing 4 mA, 8 mA drivers sourcing 8 mA.

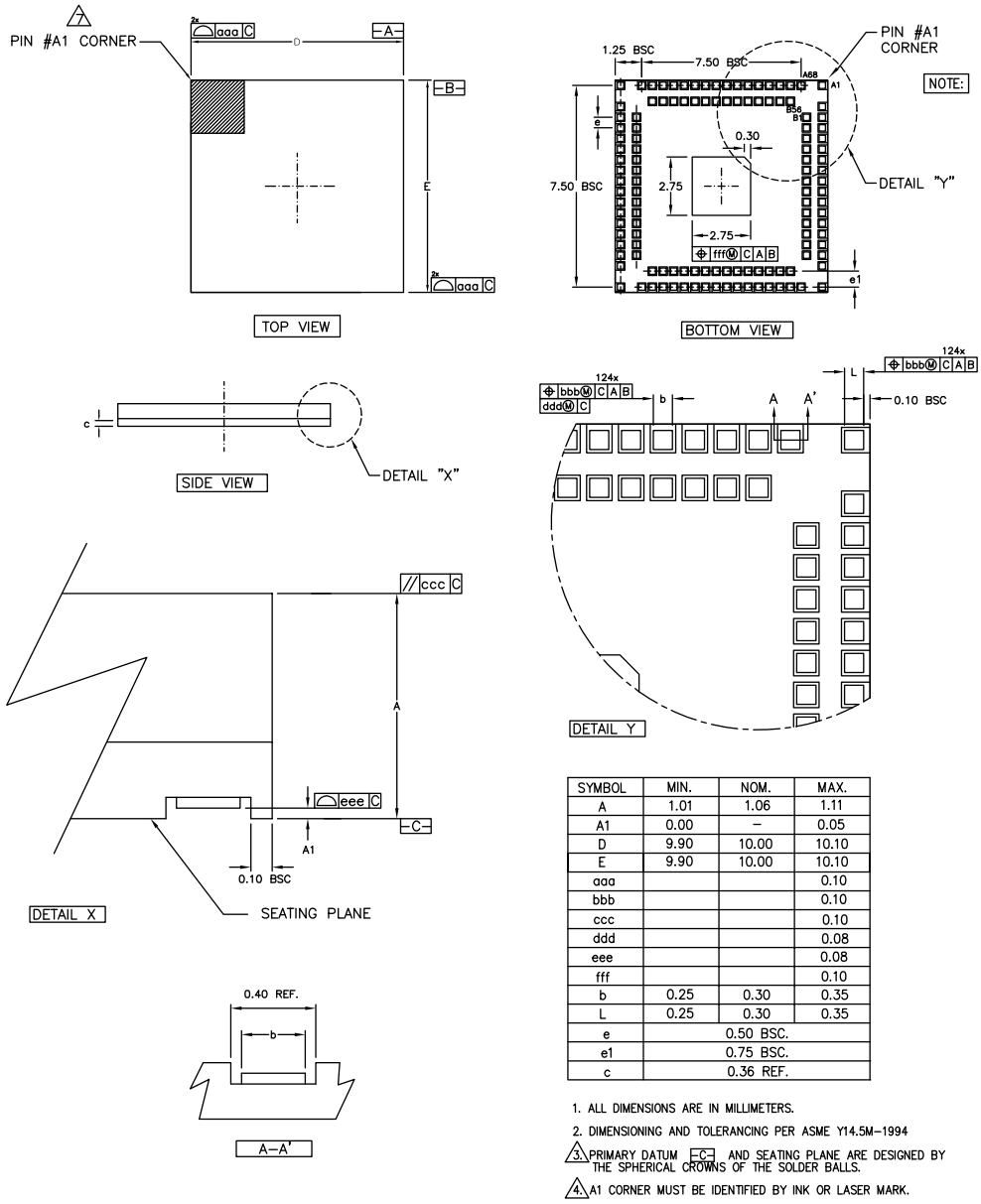
D Used to guarantee logic state for an I/O when high impedance. The internal pull-ups/pull-downs should not be used to pull external circuitry.

11.3 ESD Stress Voltage

Figure 20: ESD stress voltage

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
HBM	Human body model	-2.00		2.00	KV	
MM	Machine model	-200		200	V	

12 Package Information



SYMBOL	MIN.	NOM.	MAX.
A	1.01	1.06	1.11
A1	0.00	–	0.05
D	9.90	10.00	10.10
E	9.90	10.00	10.10
aaa			0.10
bbb			0.10
ccc			0.10
ddd			0.08
eee			0.08
fff			0.10
b	0.25	0.30	0.35
L	0.25	0.30	0.35
e	0.50 BSC.		
e1	0.75 BSC.		
c	0.36 REF.		

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
3. PRIMARY DATUM -C- AND SEATING PLANE ARE DESIGNED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. A1 CORNER MUST BE IDENTIFIED BY INK OR LASER MARK.

B.19 Debug scratch: 0x20 .. 0x27

A set of registers used by the debug ROM to communicate with an external debugger, for example over JTAG. This is the same set of registers as the Debug Scratch registers in the xCORE tile configuration.

0x20 .. 0x27: Debug scratch

Bits	Perm	Init	Description
31:0	DRW		Value.

B.20 Instruction breakpoint address: 0x30 .. 0x33

This register contains the address of the instruction breakpoint. If the PC matches this address, then a debug interrupt will be taken. There are four instruction breakpoints that are controlled individually.

0x30 .. 0x33: Instruction breakpoint address

Bits	Perm	Init	Description
31:0	DRW		Value.

B.21 Instruction breakpoint control: 0x40 .. 0x43

This register controls which logical cores may take an instruction breakpoint, and under which condition.

0x40 .. 0x43: Instruction breakpoint control

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	DRW	0	A bit for each logical core in the tile allowing the breakpoint to be enabled individually for each logical core.
15:2	RO	-	Reserved
1	DRW	0	Set to 1 to cause an instruction breakpoint if the PC is not equal to the breakpoint address. By default, the breakpoint is triggered when the PC is equal to the breakpoint address.
0	DRW	0	When 1 the instruction breakpoint is enabled.

B.22 Data watchpoint address 1: 0x50 .. 0x53

This set of registers contains the first address for the four data watchpoints.

0x80 .. 0x83: Resources breakpoint mask

Bits	Perm	Init	Description
31:0	DRW		Value.

B.26 Resources breakpoint value: 0x90 .. 0x93

This set of registers contains the value for the four resource watchpoints.

0x90 .. 0x93: Resources breakpoint value

Bits	Perm	Init	Description
31:0	DRW		Value.

B.27 Resources breakpoint control register: 0x9C .. 0x9F

This set of registers controls each of the four resource watchpoints.

0x9C .. 0x9F: Resources breakpoint control register

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	DRW	0	A bit for each logical core in the tile allowing the breakpoint to be enabled individually for each logical core.
15:2	RO	-	Reserved
1	DRW	0	By default, resource watchpoints trigger when the resource id masked with the set Mask equals the Value. If set to 1, resource watchpoints trigger when the resource id masked with the set Mask is not equal to the Value.
0	DRW	0	When 1 the instruction breakpoint is enabled.

C.16 SR of logical core 1: 0x61

0x61: SR of logical core 1

Bits	Perm	Init	Description
31:0	RO		Value.

C.17 SR of logical core 2: 0x62

0x62: SR of logical core 2

Bits	Perm	Init	Description
31:0	RO		Value.

C.18 SR of logical core 3: 0x63

0x63: SR of logical core 3

Bits	Perm	Init	Description
31:0	RO		Value.

C.19 SR of logical core 4: 0x64

0x64: SR of logical core 4

Bits	Perm	Init	Description
31:0	RO		Value.

C.20 Chanend status: 0x80 .. 0x9F

These registers record the status of each channel-end on the tile.

0x80 .. 0x9F: Chanend status

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		00 - ChannelEnd, 01 - ERROR, 10 - PSCTL, 11 - Idle.
23:16	RO		Based on SRC_TARGET_TYPE value, it represents channelEnd ID or Idle status.
15:6	RO	-	Reserved
5:4	RO		Two-bit network identifier
3	RO	-	Reserved
2	RO		1 when the current packet is considered junk and will be thrown away.
1	RO	0	Set to 1 if the switch is routing data into the link, and if a route exists from another link.
0	RO	0	Set to 1 if the link is routing data into the switch, and if a route is created to another link on the switch.

0x01: System switch description

Bits	Perm	Init	Description
31:24	RO	-	Reserved
23:16	RO		Number of links on the switch.
15:8	RO		Number of cores that are connected to this switch.
7:0	RO		Number of links per processor.

D.3 Switch configuration: 0x04

This register enables the setting of two security modes (that disable updates to the PLL or any other registers) and the header-mode.

0x04: Switch configuration

Bits	Perm	Init	Description
31	RO	0	Set to 1 to disable any write access to the configuration registers in this switch.
30:9	RO	-	Reserved
8	RO	0	Set to 1 to disable updates to the PLL configuration register.
7:1	RO	-	Reserved
0	RO	0	Header mode. Set to 1 to enable 1-byte headers. This must be performed on all nodes in the system.

D.4 Switch node identifier: 0x05

This register contains the node identifier.

0x05: Switch node identifier

Bits	Perm	Init	Description
31:16	RO	-	Reserved
15:0	RW	0	The unique 16-bit ID of this node. This ID is matched most-significant-bit first with incoming messages for routing purposes.

D.5 PLL settings: 0x06

An on-chip PLL multiplies the input clock up to a higher frequency clock, used to clock the I/O, processor, and switch, see Oscillator. Note: a write to this register will cause the tile to be reset.

0x06: PLL settings

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:23	RW		OD: Output divider value The initial value depends on pins MODE0 and MODE1.
22:21	RO	-	Reserved
20:8	RW		F: Feedback multiplication ratio The initial value depends on pins MODE0 and MODE1.
7	RO	-	Reserved
6:0	RW		R: Oscilator input divider value The initial value depends on pins MODE0 and MODE1.

D.6 System switch clock divider: 0x07

Sets the ratio of the PLL clock and the switch clock.

0x07: System switch clock divider

Bits	Perm	Init	Description
31:16	RO	-	Reserved
15:0	RW	0	Switch clock divider. The PLL clock will be divided by this value plus one to derive the switch clock.

D.7 Reference clock: 0x08

Sets the ratio of the PLL clock and the reference clock used by the node.

0x08: Reference clock

Bits	Perm	Init	Description
31:16	RO	-	Reserved
15:0	RW	3	Architecture reference clock divider. The PLL clock will be divided by this value plus one to derive the 100 MHz reference clock.

D.8 Directions 0-7: 0x0C

This register contains eight directions, for packets with a mismatch in bits 7..0 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

0x0C: Directions 0-7

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose first mismatching bit is 7.
27:24	RW	0	The direction for packets whose first mismatching bit is 6.
23:20	RW	0	The direction for packets whose first mismatching bit is 5.
19:16	RW	0	The direction for packets whose first mismatching bit is 4.
15:12	RW	0	The direction for packets whose first mismatching bit is 3.
11:8	RW	0	The direction for packets whose first mismatching bit is 2.
7:4	RW	0	The direction for packets whose first mismatching bit is 1.
3:0	RW	0	The direction for packets whose first mismatching bit is 0.

D.9 Directions 8-15: 0x0D

This register contains eight directions, for packets with a mismatch in bits 15..8 of the node-identifier. The direction in which a packet will be routed is goverened by the most significant mismatching bit.

0x0D: Directions 8-15

Bits	Perm	Init	Description
31:28	RW	0	The direction for packets whose first mismatching bit is 15.
27:24	RW	0	The direction for packets whose first mismatching bit is 14.
23:20	RW	0	The direction for packets whose first mismatching bit is 13.
19:16	RW	0	The direction for packets whose first mismatching bit is 12.
15:12	RW	0	The direction for packets whose first mismatching bit is 11.
11:8	RW	0	The direction for packets whose first mismatching bit is 10.
7:4	RW	0	The direction for packets whose first mismatching bit is 9.
3:0	RW	0	The direction for packets whose first mismatching bit is 8.

D.10 DEBUG_N configuration: 0x10

Configures the behavior of the DEBUG_N pin.

0x10: DEBUG_N configuration

Bits	Perm	Init	Description
31:2	RO	-	Reserved
1	RW	0	Set to 1 to enable signals on DEBUG_N to generate DCALL on the core.
0	RW	0	When set to 1, the DEBUG_N wire will be pulled down when the node enters debug mode.

D.11 Debug source: 0x1F

Contains the source of the most recent debug event.

0x1F: Debug source

Bits	Perm	Init	Description
31:5	RO	-	Reserved
4	RW		If set, the external DEBUG_N pin is the source of the most recent debug interrupt.
3:1	RO	-	Reserved
0	RW		If set, the xCORE Tile is the source of the most recent debug interrupt.

D.12 Link status, direction, and network: 0x20 .. 0x27

These registers contain status information for low level debugging (read-only), the network number that each link belongs to, and the direction that each link is part of. The registers control links C, D, A, B, G, H, E, and F in that order.

0x20 .. 0x27: Link status, direction, and network

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		If this link is currently routing data into the switch, this field specifies the type of link that the data is routed to: 0: plink 1: external link 2: internal control link
23:16	RO	0	If the link is routing data into the switch, this field specifies the destination link number to which all tokens are sent.
15:12	RO	-	Reserved
11:8	RW	0	The direction that this this link is associated with; set for routing.
7:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, set for quality of service.
3	RO	-	Reserved
2	RO	0	Set to 1 if the current packet is junk and being thrown away. A packet is considered junk if, for example, it is not routable.
1	RO	0	Set to 1 if the switch is routing data into the link, and if a route exists from another link.
0	RO	0	Set to 1 if the link is routing data into the switch, and if a route is created to another link on the switch.

Bits	Perm	Init	Description
31	RW	0	Write '1' to this bit to enable the link, write '0' to disable it. This bit controls the muxing of ports with overlapping links.
30	RW	0	Set to 0 to operate in 2 wire mode or 1 to operate in 5 wire mode
29:28	RO	-	Reserved
27	RO	0	Set to 1 on error: an RX buffer overflow or illegal token encoding has been received. This bit clears on reading.
26	RO	0	1 if this end of the link has issued credit to allow the remote end to transmit.
25	RO	0	1 if this end of the link has credits to allow it to transmit.
24	WO	0	Set to 1 to initialize a half-duplex link. This clears this end of the link's credit and issues a HELLO token; the other side of the link will reply with credits. This bit is self-clearing.
23	WO	0	Set to 1 to reset the receiver. The next symbol that is detected will be assumed to be the first symbol in a token. This bit is self-clearing.
22	RO	-	Reserved
21:11	RW	0	The number of system clocks between two subsequent transitions within a token
10:0	RW	0	The number of system clocks between two subsequent transmit tokens.

0x80 .. 0x87: Link configuration and initialization

D.15 Static link configuration: 0xA0 .. 0xA7

These registers are used for static (ie, non-routed) links. When a link is made static, all traffic is forwarded to the designated channel end and no routing is attempted. The registers control links C, D, A, B, G, H, E, and F in that order.

Bits	Perm	Init	Description
31	RW	0	Enable static forwarding.
30:5	RO	-	Reserved
4:0	RW	0	The destination channel end on this node that packets received in static mode are forwarded to.

0xA0 .. 0xA7: Static link configuration

J Associated Design Documentation

Document Title	Information	Document Number
Estimating Power Consumption For XS1-L Devices	Power consumption	X4271
Programming XC on XMOS Devices	Timers, ports, clocks, cores and channels	X9577
xTIMEcomposer User Guide	Compilers, assembler and linker/mapper Timing analyzer, xScope, debugger Flash and OTP programming utilities	X3766

K Related Documentation

Document Title	Information	Document Number
The XMOS XS1 Architecture	ISA manual	X7879
XS1 Port I/O Timing	Port timings	X5821
xCONNECT Architecture	Link, switch and system information	X4249
XS1-L Link Performance and Design Guidelines	Link timings	X2999
XS1-L Clock Frequency Control	Advanced clock control	X1433
XS1-L Active Power Conservation	Low-power mode during idle	X7411

L Revision History

Date	Description
2013-01-30	New datasheet - revised part numbering
2013-02-26	New multicore microcontroller introduction Moved configuration sections to appendices
2013-07-19	Updated Features list with available ports and links - Section 2 Simplified link bits in Signal Description - Section 4 New JTAG, xSCOPE and Debugging appendix - Section G New Schematics Design Check List - Section H New PCB Layout Design Check List - Section I
2013-09-16	Removed references to PCU. Pins set to GND - Section 3
2013-12-09	Added Industrial Ambient Temperature - Section 11.1
2013-12-17	Added references to PCU - Section 3 and 9.1
2014-03-25	Updated BOTTOM VIEW in mechanical drawing - Section 12
2014-06-25	Added PCU_GATE, PCU_CLK, PCU_VDD, PCU_VDDIO to Schematics Checklist - Section H
2015-04-14	Updated Introduction - Section 1; Pin Configuration - Section 3; Signal Description - Section 4

Copyright © 2015, All Rights Reserved.

Xmos Ltd. is the owner or licensee of this design, code, or Information (collectively, the “Information”) and is providing it to you “AS IS” with no warranty of any kind, express or implied and shall have no liability in relation to its use. Xmos Ltd. makes no representation that the Information, or any particular implementation thereof, is or will be free from any claims of infringement and again, shall have no liability in relation to any such claims.